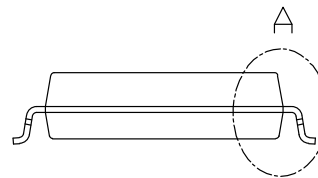
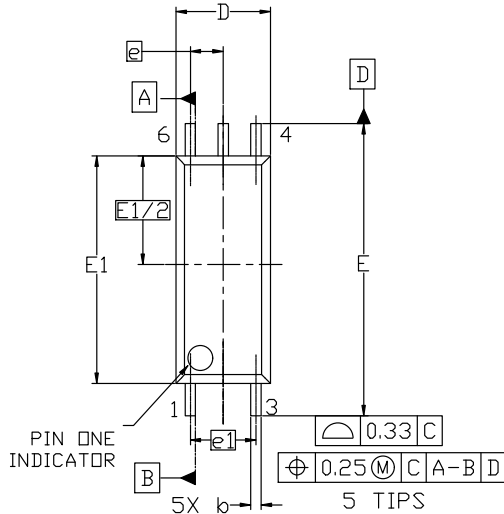


**SOIC5 (6) 3.65x8.80x2.55, 1.27P**  
**CASE 752AG**  
**ISSUE B**

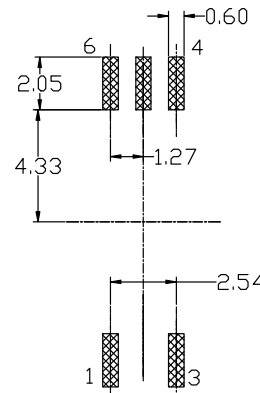
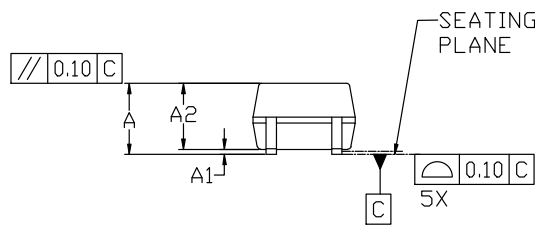
DATE 24 JUL 2023

NOTES: UNLESS OTHERWISE SPECIFIED

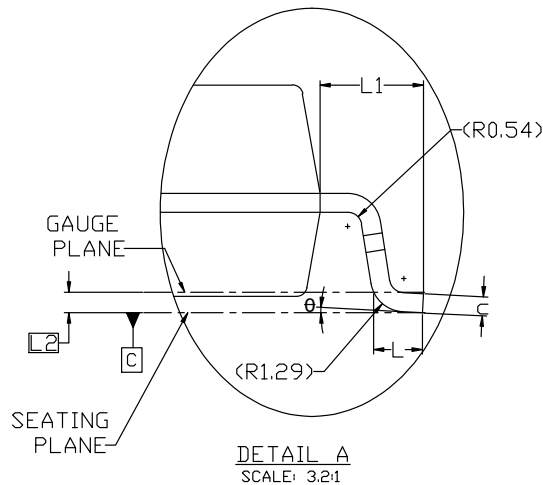
- A) THIS PACKAGE DOES NOT CONFORM TO ANY STANDARD.  
 B) ALL DIMENSIONS ARE IN MILLIMETERS.  
 C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS  
 D) DRAWING CONFORMS TO ASME Y14.5M-1994



DIM	MILLIMETER		
	MIN.	NOM.	MAX.
A	--	--	2.95
A1	0.10	0.20	0.30
A2	2.45	2.55	2.65
b	0.31	0.41	0.51
c	0.19	0.22	0.25
D	3.55	3.65	3.75
E	11.20	11.30	11.40
E1	8.70	8.80	8.90
E1/2	4.20 BSC		
e	1.27 BSC		
e1	2.54 BSC		
L	0.44	0.59	0.74
L1	1.15	1.25	1.35
L2	0.25 BSC		
θ	0°	--	8°



LAND PATTERN  
 RECOMMENDATION



\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERM/D.

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<b>DESCRIPTION:</b>	<b>SOIC5 (6) 3.65x8.80x2.55, 1.27P</b>	<b>PAGE 1 OF 1</b>

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